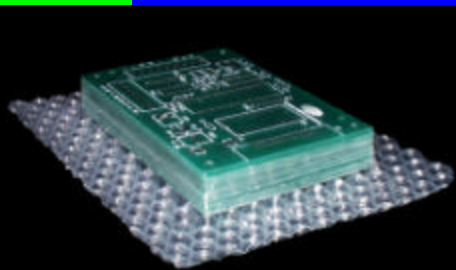


Printed Circuit Packaging Film

THE MOISTURE BARRIER



- Amine Free
- No Animal Fats
- Non Reactive
- Non Corrosive



Product Features

- Developed specifically for the Printed Circuit Industry.
- Excellent moisture barrier
- Improved package integrity.
- Excellent Formability.
- Resists pinholing.
- Available in clear or antistatic.

Dart Impact Strength in Grams (Exceeds Maximum Dart Availability)		500
Tear Resistance ASTM D1922 (Grams)	MD(Grams) TD(Grams)	1600+ 1600+
Tensile Strength ASTM D882 (PSI)	MD(PSI) TD(PSI)	9800 9100
Elongation	MD(%)	1457
Anti Stat		3%
Surface Resistivity		<10 OHMS/SQ
Static Decay		<2.3 sec.
Water Vapor (Thickness 0.010) (g/24hr. M ² @ 23°C.50% RH)		<.1
Silicones, Polysulfides, Ionic Sulfur Compounds (Not used in Manufacturing Process)		n/a
Contact Corrosion:	Copper Tin/Lead Gold	none none none
Part #'s	Clear Anti Stat	
SK-2610P		
SK2610AS		



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